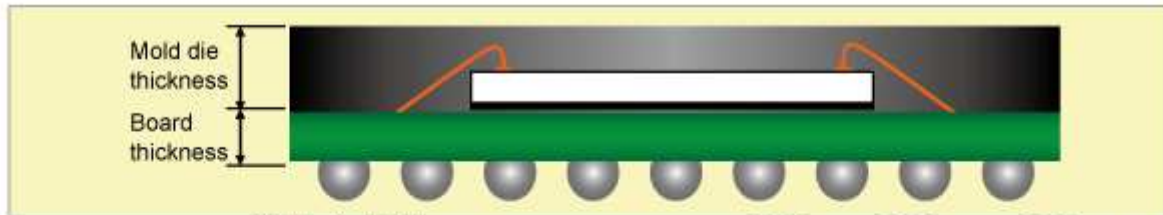


# BGA/LGA

# BGA/LGA



Mold die thickness	0.70	0.80	0.90mm
Board thickness	0.20	~	0.48mm
Ball diameter	φ0.20	~	0.60mm

\* Any size package that customer requires is possible to product with setting by combination of molding die and board thickness

## ■ BGA Package lineup

We can make these products as a lineup.

Package	Package Size(mm)		Ball Pitch (mm)	Pin Count														
	D	E		44	57	65	72	85	96	97	104	108	113	119	128	132	156	
BGA	4.0	4.0	0.5	●														
	5.0	5.0	0.5	●	●		●											
	6.0	6.0	0.5			●		●		●								
	7.0	7.0	0.5											●				
	8.0	8.0	0.5								●					●		
			0.65						●		●		●					
	10	10	0.8									●						
	12.0	12.0	0.8														●	
	13.0	13.0	1.0									●						
14.0	22.0	1.27											●					

# BGA/LGA

## ■ BGA Package lineup

Package	Package Size(mm)		Ball Pitch (mm)	Pin Count												
	D	E		164	176	181	208	224	256	264	277	281	324	329	480	676
BGA	6.0	6.0	0.4			●										
	13.0	13.0	0.65								●	●				
			0.8		●											
	14.0	14.0	1.0	●												
	15.0	15.0	0.5												●	
			0.8										●			
	17.0	17.0	1.0				●									
			1.27	●												
	18.0	12.0	0.8					●								
	18.0	18.0	0.65						●	●						
	19.0	19.0	0.8										●			
	21.0	21.0	1.0											●		
27.0	27.0	1.0													●	



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